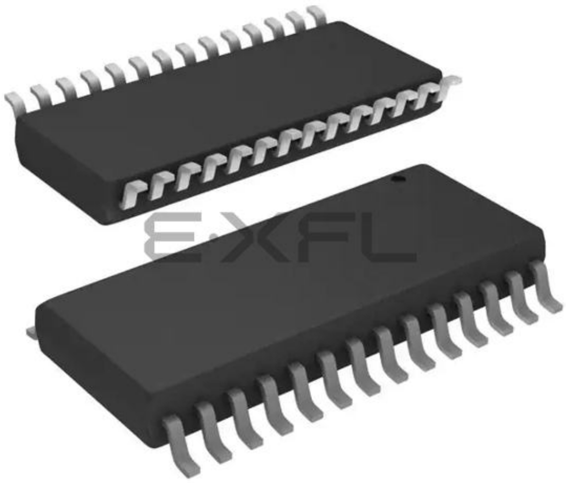

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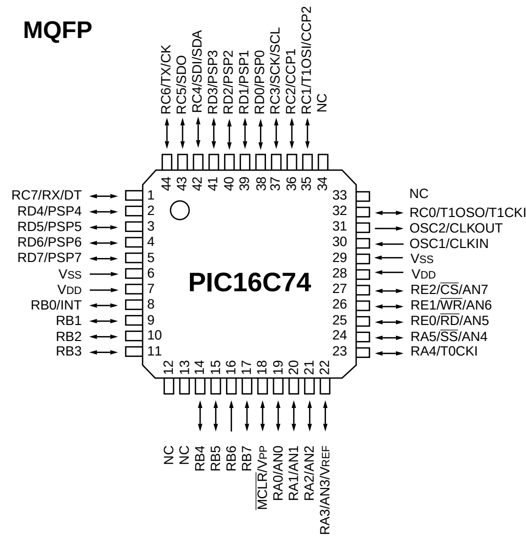
Applications of "Embedded - Microcontrollers"

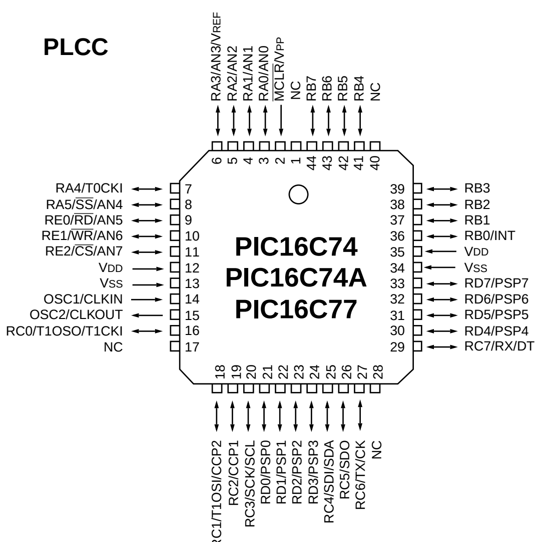
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c73a-20i-so

Pin Diagrams (Cont.'d)

MQFP



PLCC



MQFP
TQFP

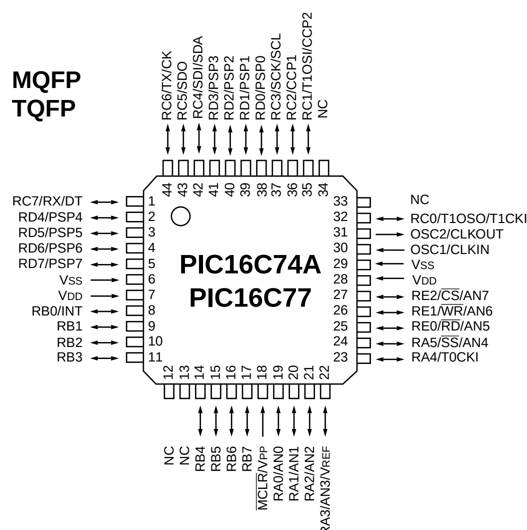
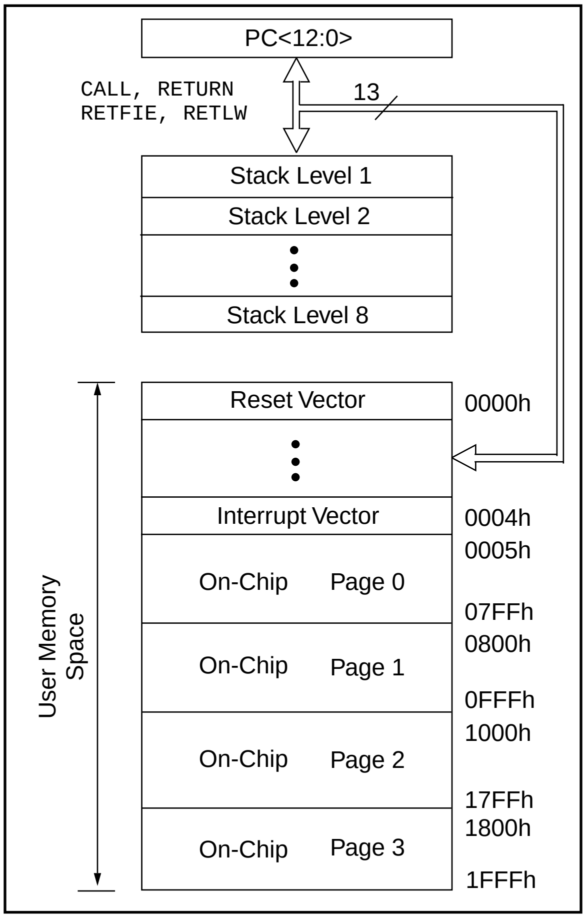


FIGURE 4-3: PIC16C76/77 PROGRAM MEMORY MAP AND STACK



4.2 Data Memory Organization

Applicable Devices						
72	73	73A	74	74A	76	77

The data memory is partitioned into multiple banks which contain the General Purpose Registers and the Special Function Registers. Bits RP1 and RP0 are the bank select bits.

RP1:RP0 (STATUS<6:5>)
= 00 → Bank0
= 01 → Bank1
= 10 → Bank2
= 11 → Bank3

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain special function registers. Some “high use” special function registers from one bank may be mirrored in another bank for code reduction and quicker access.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly through the File Select Register FSR (Section 4.5).

4.2.2.5 PIR1 REGISTER

Applicable Devices						
72	73	73A	74	74A	76	77

This register contains the individual flag bits for the Peripheral interrupts.

Note:	Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 4-12: PIR1 REGISTER PIC16C72 (ADDRESS 0Ch)

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ADIF	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7: **Unimplemented:** Read as '0'

bit 6: **ADIF**: A/D Converter Interrupt Flag bit
1 = An A/D conversion completed (must be cleared in software)
0 = The A/D conversion is not complete

bit 5-4: **Unimplemented**: Read as '0'

bit 3: **SSPIF**: Synchronous Serial Port Interrupt Flag bit
1 = The transmission/reception is complete (must be cleared in software)
0 = Waiting to transmit/receive

bit 2: **CCP1IF**: CCP1 Interrupt Flag bit
Capture Mode
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare Mode
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM Mode
Unused in this mode

bit 1: **TMR2IF**: TMR2 to PR2 Match Interrupt Flag bit
1 = TMR2 to PR2 match occurred (must be cleared in software)
0 = No TMR2 to PR2 match occurred

bit 0: **TMR1IF**: TMR1 Overflow Interrupt Flag bit
1 = TMR1 register overflowed (must be cleared in software)
0 = TMR1 register did not overflow

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

TABLE 10-5: REGISTERS ASSOCIATED WITH PWM AND TIMER2

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF[1,2]	ADIF	RCIF[2]	TXIF[2]	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh[2]	PIR2	—	—	—	—	—	—	—	CCP2IF	---- ---0	---- ---0
8Ch	PIE1	PSPIE[1,2]	ADIE	RCIE[2]	TXIE[2]	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh[2]	PIE2	—	—	—	—	—	—	—	CCP2IE	---- ---0	---- ---0
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
11h	TMR2	Timer2 module's register								0000 0000	0000 0000
92h	PR2	Timer2 module's period register								1111 1111	1111 1111
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/Compare/PWM register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
1Bh[2]	CCPR2L	Capture/Compare/PWM register2 (LSB)								xxxx xxxx	uuuu uuuu
1Ch[2]	CCPR2H	Capture/Compare/PWM register2 (MSB)								xxxx xxxx	uuuu uuuu
1Dh[2]	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by PWM and Timer2.
Note 1: Bits PSPIE and PSPIF are reserved on the PIC16C73/73A/76, always maintain these bits clear.
2: The PIC16C72 does not have a Parallel Slave Port, USART or CCP2 module, these bits are unimplemented, read as '0'.

Steps to follow when setting up an Asynchronous Reception:

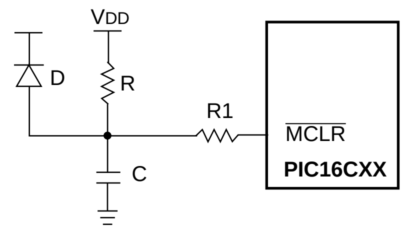
1. Initialize the SPBRG register for the appropriate baud rate. If a high speed baud rate is desired, set bit BRGH. (Section 12.1).
2. Enable the asynchronous serial port by clearing bit SYNC, and setting bit SPEN.
3. If interrupts are desired, then set enable bit RCIE.
4. If 9-bit reception is desired, then set bit RX9.
5. Enable the reception by setting bit CREN.
6. Flag bit RCIF will be set when reception is complete and an interrupt will be generated if enable bit RCIE was set.
7. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
8. Read the 8-bit received data by reading the RCREG register.
9. If any error occurred, clear the error by clearing enable bit CREN.

TABLE 12-7: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
1Ah	RCREG	USART Receive Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Reception.
Note 1: Bits PSPIE and PSPIF are reserved on the PIC16C73/73A/76, always maintain these bits clear.

FIGURE 14-13: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)

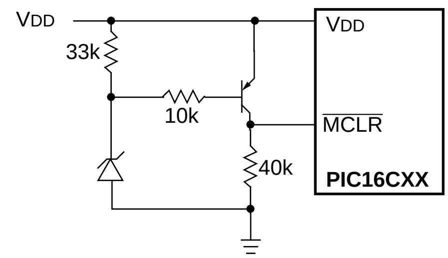


Note 1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into $\overline{\text{MCLR}}$ from external capacitor C in the event of $\overline{\text{MCLR}}$/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

FIGURE 14-14: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1

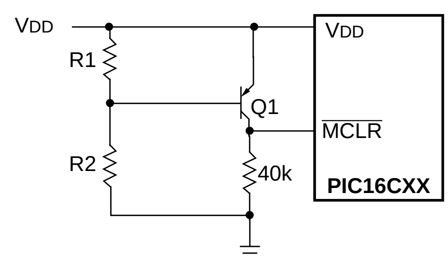


Note 1: This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.

2: Internal brown-out detection on the PIC16C72/73A/74A/76/77 should be disabled when using this circuit.

3: Resistors should be adjusted for the characteristics of the transistor.

FIGURE 14-15: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2



Note 1: This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

2: Internal brown-out detection on the PIC16C72/73A/74A/76/77 should be disabled when using this circuit.

3: Resistors should be adjusted for the characteristics of the transistor.

14.5 Interrupts

Applicable Devices						
72	73	73A	74	74A	76	77

The PIC16C7X family has up to 12 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note:	Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, `RETFIE`, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 14-17). The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

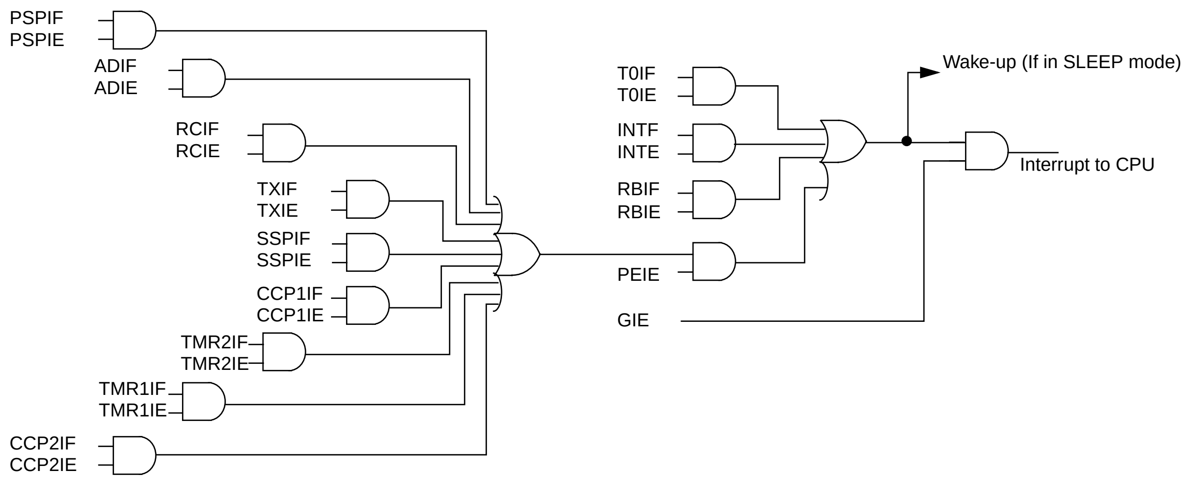
Note: For the PIC16C73/74, if an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the `RETFIE` instruction). The events that would cause this to occur are:

1. An instruction clears the GIE bit while an interrupt is acknowledged.
2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
3. The Interrupt Service Routine completes with the execution of the `RETFIE` instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.

Perform the following to ensure that interrupts are globally disabled:

```
LOOP BCF   INTCON, GIE  ; Disable global
                        ;  interrupt bit
     BTFSC INTCON, GIE  ; Global interrupt
                        ;   disabled?
     GOTO  LOOP         ; NO, try again
        :               ;   Yes, continue
                        ;   with program
                        ;   flow
```

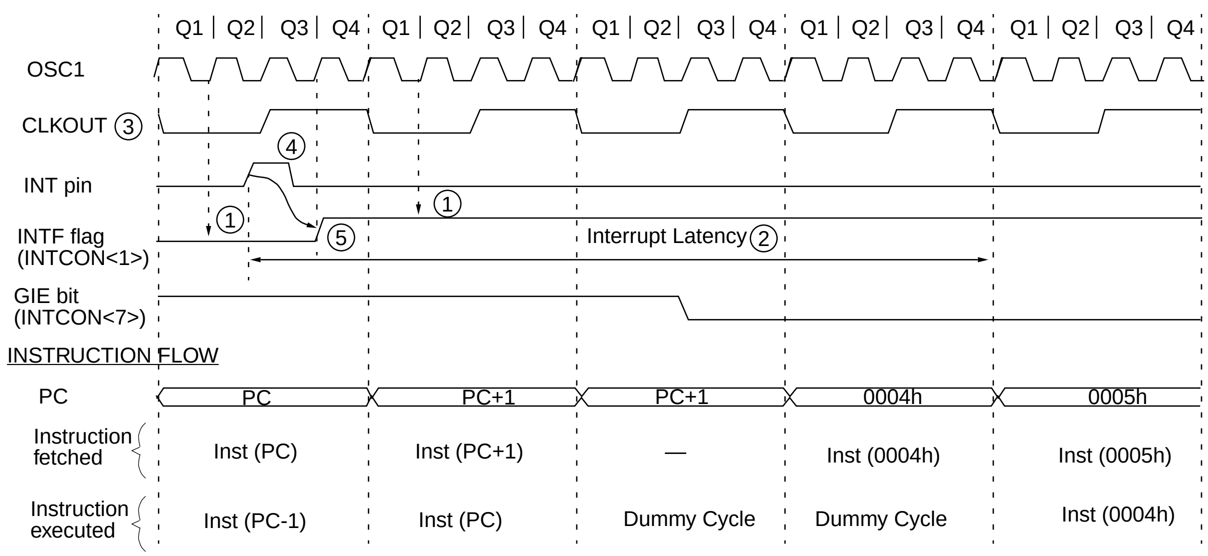
FIGURE 14-16: INTERRUPT LOGIC



The following table shows which devices have which interrupts.

Device	T0IF	INTF	RBIF	PSPIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	CCP2IF
PIC16C72	Yes	Yes	Yes	-	Yes	-	-	Yes	Yes	Yes	Yes	-
PIC16C73	Yes	Yes	Yes	-	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C73A	Yes	Yes	Yes	-	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C74	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C74A	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C76	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C77	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

FIGURE 14-17: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).
2: Interrupt latency = 3-4 Tcy where Tcy = instruction cycle time.
Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.
3: CLKOUT is available only in RC oscillator mode.
4: For minimum width of INT pulse, refer to AC specs.
5: INTF is enabled to be set anytime during the Q4-Q1 cycles.

14.7 Watchdog Timer (WDT)

Applicable Devices						
72	73	73A	74	74A	76	77

The Watchdog Timer is as a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device has been stopped, for example, by execution of a `SLEEP` instruction. During normal operation, a WDT time-out generates a device RESET (Watchdog Timer Reset). If the device is in SLEEP mode, a WDT time-out causes the device to wake-up and continue with normal operation (Watchdog Timer Wake-up). The WDT can be permanently disabled by clearing configuration bit WDTE (Section 14.1).

14.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, V_{DD} and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The `CLRWDT` and `SLEEP` instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device RESET condition.

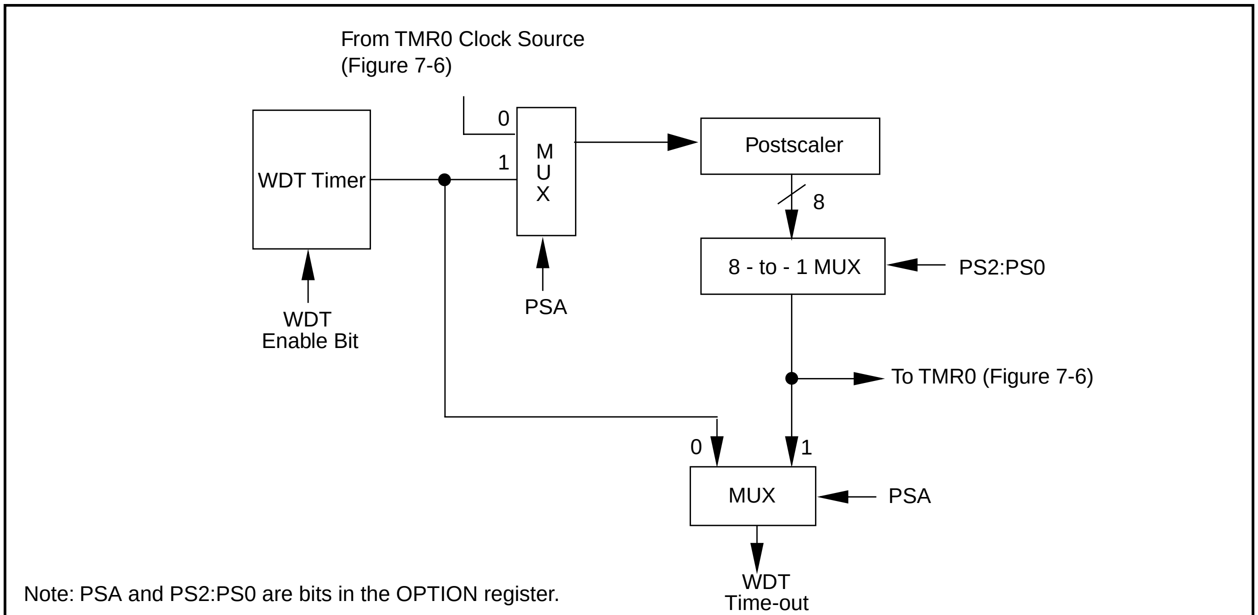
The $\overline{TO}$ bit in the STATUS register will be cleared upon a Watchdog Timer time-out.

14.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken into account that under worst case conditions (V_{DD} = Min., Temperature = Max., and max. WDT prescaler) it may take several seconds before a WDT time-out occurs.

Note: When a `CLRWDT` instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed.

FIGURE 14-18: WATCHDOG TIMER BLOCK DIAGRAM



Note: PSA and PS2:PS0 are bits in the OPTION register.

FIGURE 14-19: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	**(1)**	BODEN(1)	CP1	CP0	PWRTE(1)	WDTE	FOSC1	FOSC0
81h,181h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer.
Note 1: See Figure 14-1, and Figure 14-2 for operation of these bits.

TABLE 15-2: PIC16CXX INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode				Status Affected	Notes
				MSb			LSb		
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	**f, d**	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	**f, d**	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	**f**	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	**-**	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	**f, d**	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	**f, d**	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	**f, d**	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	**f, d**	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	**f, d**	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	**f, d**	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	**f, d**	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	**f**	Move W to f	1	00	0000	lfff	ffff		
NOP	**-**	No Operation	1	00	0000	0xx0	0000		
RLF	**f, d**	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	1,2
RRF	**f, d**	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	1,2
SUBWF	**f, d**	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	**f, d**	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	**f, d**	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	**f, b**	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	**f, b**	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	**f, b**	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	**f, b**	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL AND CONTROL OPERATIONS									
ADDLW	**k**	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	**k**	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	**k**	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	**-**	Clear Watchdog Timer	1	00	0000	0110	0100	$\overline{TO}$,$\overline{PD}$	
GOTO	**k**	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	**k**	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	**k**	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	**-**	Return from interrupt	2	00	0000	0000	1001		
RETLW	**k**	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	**-**	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	**-**	Go into standby mode	1	00	0000	0110	0011	$\overline{TO}$,$\overline{PD}$	
SUBLW	**k**	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	**k**	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

15.1 Instruction Descriptions

ADDLW — Add Literal and W

Syntax: [*label*] ADDLW k

Operands: $0 \le k \le 255$

Operation: (W) + k → (W)

Status Affected: C, DC, Z

Encoding:

11	111x	kkkk	kkkk

Description: The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example: `ADDLW 0x15`

Before Instruction
W = 0x10
After Instruction
W = 0x25

ANDLW — AND Literal with W

Syntax: [*label*] ANDLW k

Operands: $0 \le k \le 255$

Operation: (W) .AND. (k) → (W)

Status Affected: Z

Encoding:

11	1001	kkkk	kkkk

Description: The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal "k"	Process data	Write to W

Example `ANDLW 0x5F`

Before Instruction
W = 0xA3
After Instruction
W = 0x03

ADDWF — Add W and f

Syntax: [*label*] ADDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) + (f) → (destination)

Status Affected: C, DC, Z

Encoding:

00	0111	dfff	ffff

Description: Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example `ADDWF FSR, 0`

Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0xD9
FSR = 0xC2

ANDWF — AND W with f

Syntax: [*label*] ANDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .AND. (f) → (destination)

Status Affected: Z

Encoding:

00	0101	dfff	ffff

Description: AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example `ANDWF FSR, 1`

Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0x17
FSR = 0x02

Applicable Devices	72	73	73A	74	74A	76	77

18.0 ELECTRICAL CHARACTERISTICS FOR PIC16C73/74

Absolute Maximum Ratings †

Ambient temperature under bias .... -55 to +125˚C
Storage temperature .... -65˚C to +150˚C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$. and RA4) .... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} .... -0.3 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) .... 0 to +14V
Voltage on RA4 with respect to Vss .... 0 to +14V
Total power dissipation (Note 1) 1.0W
Maximum current out of V_{SS} pin .... 300 mA
Maximum current into V_{DD} pin .... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) .... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) .... ±20 mA
Maximum output current sunk by any I/O pin .... 25 mA
Maximum output current sourced by any I/O pin .... 25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined) (Note 3) .... 200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined) (Note 3) .... 200 mA
Maximum current sunk by PORTC and PORTD (combined) (Note 3) .... 200 mA
Maximum current sourced by PORTC and PORTD (combined) (Note 3) .... 200 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

Note 3: PORTD and PORTE are not implemented on the PIC16C73.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 18-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C73-04 PIC16C74-04	PIC16C73-10 PIC16C74-10	PIC16C73-20 PIC16C74-20	PIC16LC73-04 PIC16LC74-04	JW Devices
RC	V_{DD}: 4.0V to 6.0V I_{DD}: 5 mA max. at 5.5V I_{PD}: 21 µA max. at 4V Freq: 4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 2.7 mA typ. at 5.5V I_{PD}: 1.5 µA typ. at 4V Freq: 4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 2.7 mA typ. at 5.5V I_{PD}: 1.5 µA typ. at 4V Freq: 4 MHz max.	V_{DD}: 3.0V to 6.0V I_{DD}: 3.8 mA max. at 3.0V I_{PD}: 13.5 µA max. at 3V Freq: 4 MHz max.	V_{DD}: 4.0V to 6.0V I_{DD}: 5 mA max. at 5.5V I_{PD}: 21 µA max. at 4V Freq: 4 MHz max.
XT	V_{DD}: 4.0V to 6.0V I_{DD}: 5 mA max. at 5.5V I_{PD}: 21 µA max. at 4V Freq: 4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 2.7 mA typ. at 5.5V I_{PD}: 1.5 µA typ. at 4V Freq: 4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 2.7 mA typ. at 5.5V I_{PD}: 1.5 µA typ. at 4V Freq: 4 MHz max.	V_{DD}: 3.0V to 6.0V I_{DD}: 3.8 mA max. at 3.0V I_{PD}: 13.5 µA max. at 3V Freq: 4 MHz max.	V_{DD}: 4.0V to 6.0V I_{DD}: 5 mA max. at 5.5V I_{PD}: 21 µA max. at 4V Freq: 4 MHz max.
HS	V_{DD}: 4.5V to 5.5V I_{DD}: 13.5 mA typ. at 5.5V I_{PD}: 1.5 µA typ. at 4.5V Freq: 4 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 15 mA max. at 5.5V I_{PD}: 1.5 µA typ. at 4.5V Freq: 10 MHz max.	V_{DD}: 4.5V to 5.5V I_{DD}: 30 mA max. at 5.5V I_{PD}: 1.5 µA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	V_{DD}: 4.5V to 5.5V I_{DD}: 30 mA max. at 5.5V I_{PD}: 1.5 µA typ. at 4.5V Freq: 20 MHz max.
LP	V_{DD}: 4.0V to 6.0V I_{DD}: 52.5 µA typ. at 32 kHz, 4.0V I_{PD}: 0.9 µA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	V_{DD}: 3.0V to 6.0V I_{DD}: 48 µA max. at 32 kHz, 3.0V I_{PD}: 13.5 µA max. at 3.0V Freq: 200 kHz max.	V_{DD}: 3.0V to 6.0V I_{DD}: 48 µA max. at 32 kHz, 3.0V I_{PD}: 13.5 µA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications.
It is recommended that the user select the device type that ensures the specifications required.

Applicable Devices	72	73	73A	74	74A	76	77

18.3 DC Characteristics: PIC16C73/74-04 (Commercial, Industrial) PIC16C73/74-10 (Commercial, Industrial) PIC16C73/74-20 (Commercial, Industrial) PIC16LC73/74-04 (Commercial, Industrial)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40˚C ≤ TA ≤ +85˚C for industrial and 0˚C ≤ TA ≤ +70˚C for commercial Operating voltage VDD range as described in DC spec Section 18.1 and Section 18.2.					
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15VDD	V	For entire VDD range
D030A			VSS	-	0.8V	V	4.5V ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		VSS	-	0.2VDD	V	
D032	$\overline{\text{MCLR}}$, OSC1 (in RC mode)		VSS	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		VSS	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	-	VDD	V	For entire VDD range
D042	$\overline{\text{MCLR}}$		0.8VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	μA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{\text{MCLR}}$, RA4/T0CKI		-	-	±5	μA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD - 0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D150*	**Open-Drain High Voltage**	VOD	-	-	14	V	RA4 pin

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	72	73	73A	74	74A	76	77

19.2 DC Characteristics: PIC16LC73A/74A-04 (Commercial, Industrial)

DC CHARACTERISTICS							**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40˚C ≤ T_A ≤ +85˚C for industrial and 0˚C ≤ T_A ≤ +70˚C for commercial
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	V_{DD}	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	V_{DR}	-	1.5	-	V	
D003	V_{DD} start voltage to ensure internal Power-on Reset signal	V_{POR}	-	V_{SS}	-	V	See section on Power-on Reset for details
D004*	V_{DD} rise rate to ensure internal Power-on Reset signal	S_{VDD}	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	B_{VDD}	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
D010	Supply Current (Note 2,5)	I_{DD}	-	2.0	3.8	mA	XT, RC osc configuration F_{OSC} = 4 MHz, V_{DD} = 3.0V (Note 4)
D010A			-	22.5	48	µA	LP osc configuration F_{OSC} = 32 kHz, V_{DD} = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	ΔI_{BOR}	-	350	425	µA	BOR enabled V_{DD} = 5.0V
D020 D021 D021A	Power-down Current (Note 3,5)	I_{PD}	- - -	7.5 0.9 0.9	30 5 5	µA µA µA	V_{DD} = 3.0V, WDT enabled, -40°C to +85°C V_{DD} = 3.0V, WDT disabled, 0°C to +70°C V_{DD} = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	ΔI_{BOR}	-	350	425	µA	BOR enabled V_{DD} = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which V_{DD} can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all I_{DD} measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to V_{DD}
$\overline{MCLR}$ = V_{DD}; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to V_{DD} and V_{SS}.

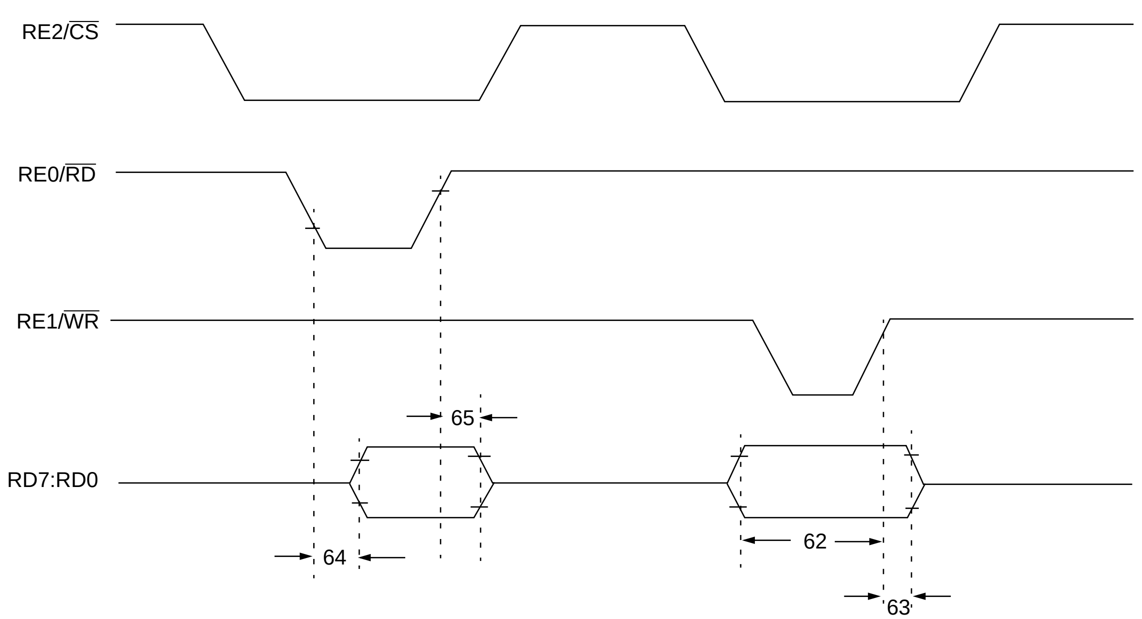
4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = V_{DD}/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base I_{DD} or I_{PD} measurement.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 19-8: PARALLEL SLAVE PORT TIMING (PIC16C74A)



Note: Refer to Figure 19-1 for load conditions

TABLE 19-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C74A)

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before $\overline{WR}$↑ or $\overline{CS}$↑ (setup time)		20 25	— —	— —	ns ns	 Extended Range Only
63*	TwrH2dtI	$\overline{WR}$↑ or $\overline{CS}$↑ to data–in invalid (hold time)	PIC16**C**74A	20	—	—	ns	
			PIC16**LC**74A	35	—	—	ns	
64	TrdL2dtV	$\overline{RD}$↓ and $\overline{CS}$↓ to data–out valid		— —	— —	80 90	ns ns	 Extended Range Only
65	TrdH2dtI	$\overline{RD}$↑ or $\overline{CS}$↓ to data–out invalid		10	—	30	ns	

* These parameters are characterized but not tested.
† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	72	73	73A	74	74A	76	77

20.5 Timing Diagrams and Specifications

FIGURE 20-2: EXTERNAL CLOCK TIMING

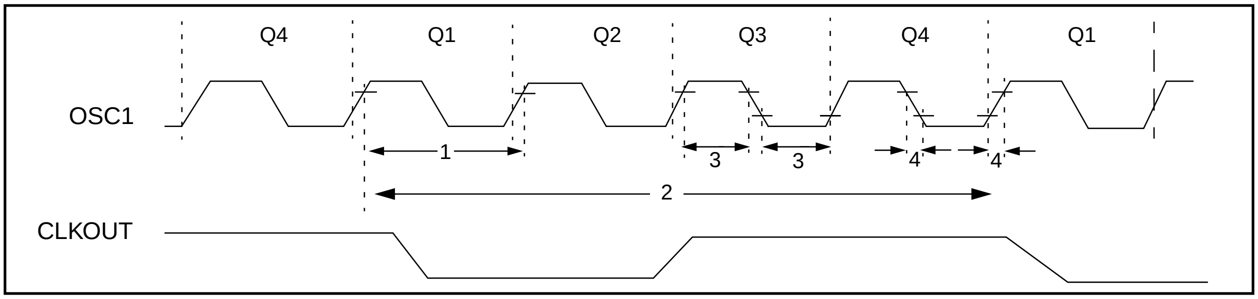


TABLE 20-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency (Note 1)**	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	**External CLKIN Period (Note 1)**	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
							HS osc mode (-20)
			50	—	250	ns	
			5	—	—	µs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	200	TCY	DC	ns	TCY = 4/FOSC
3	TosL, TosH	**External Clock in (OSC1) High or Low Time**	100	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices	72	73	73A	74	74A	76	77

FIGURE 21-16: TYPICAL IDD vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

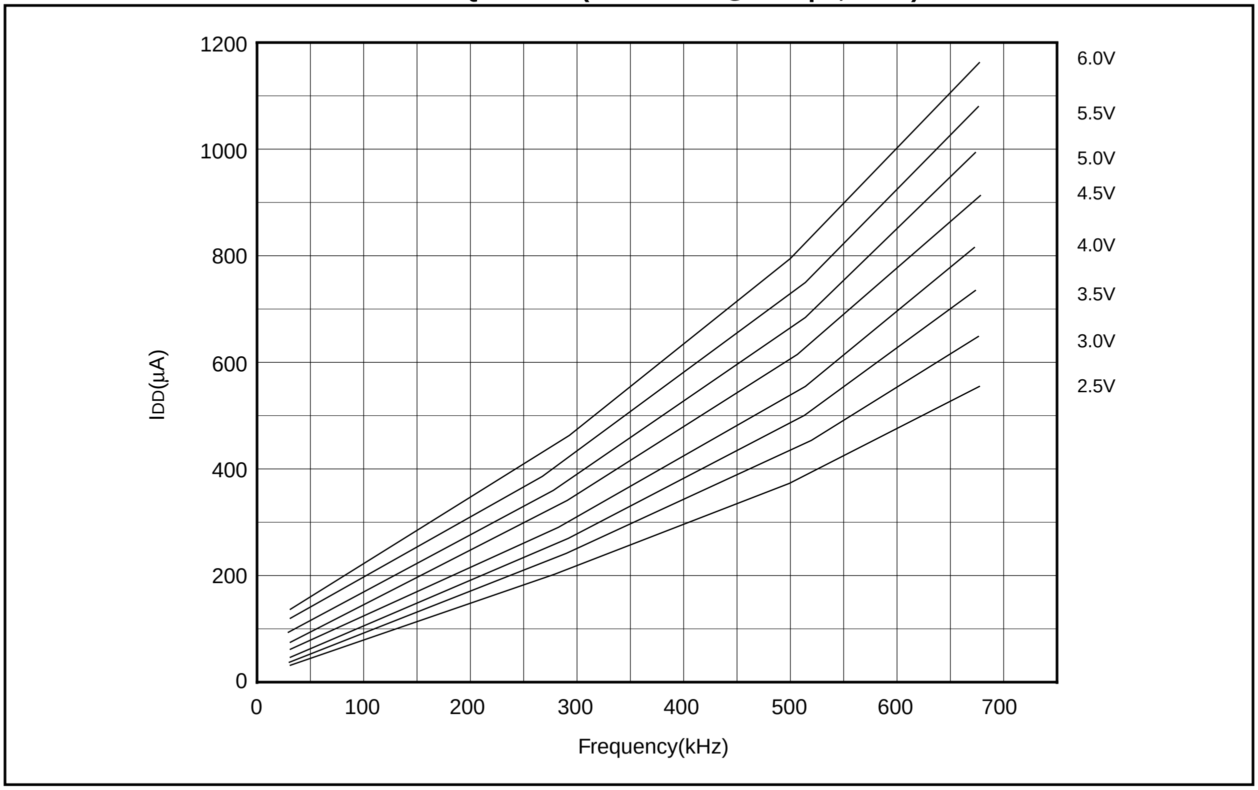
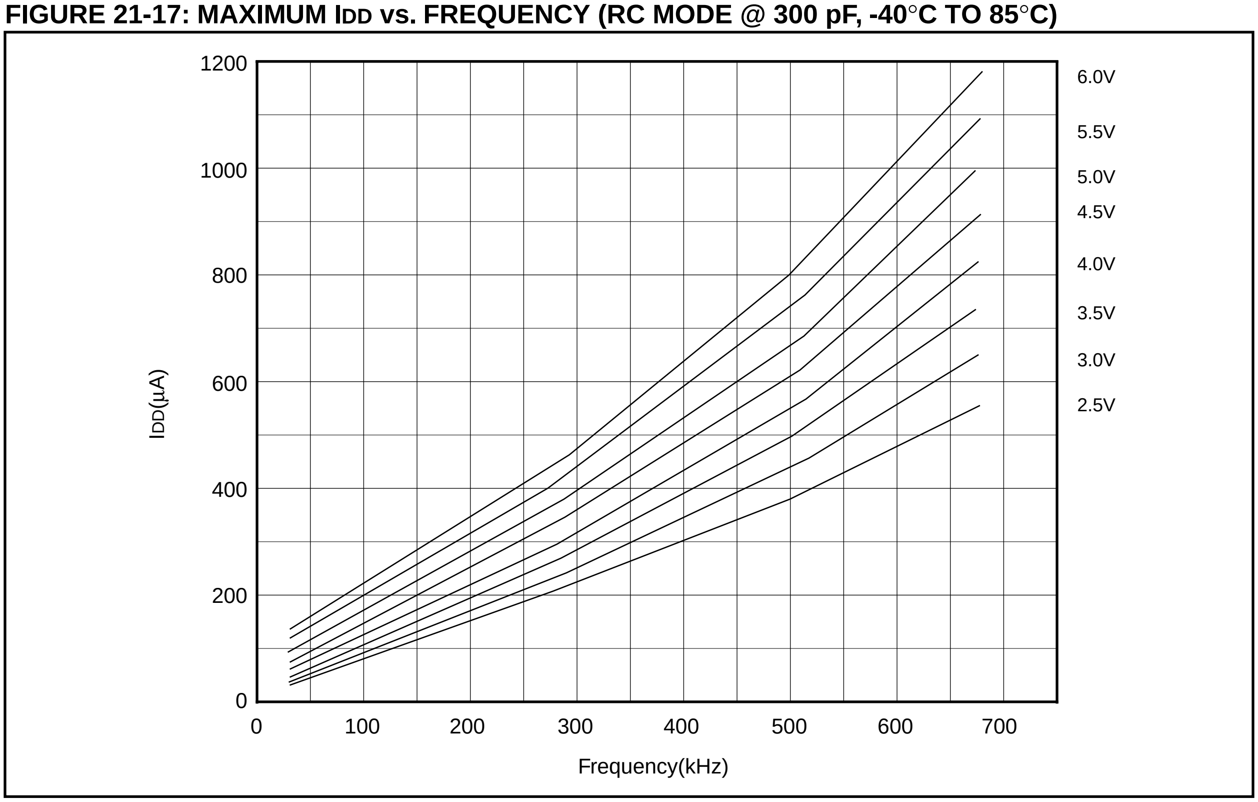
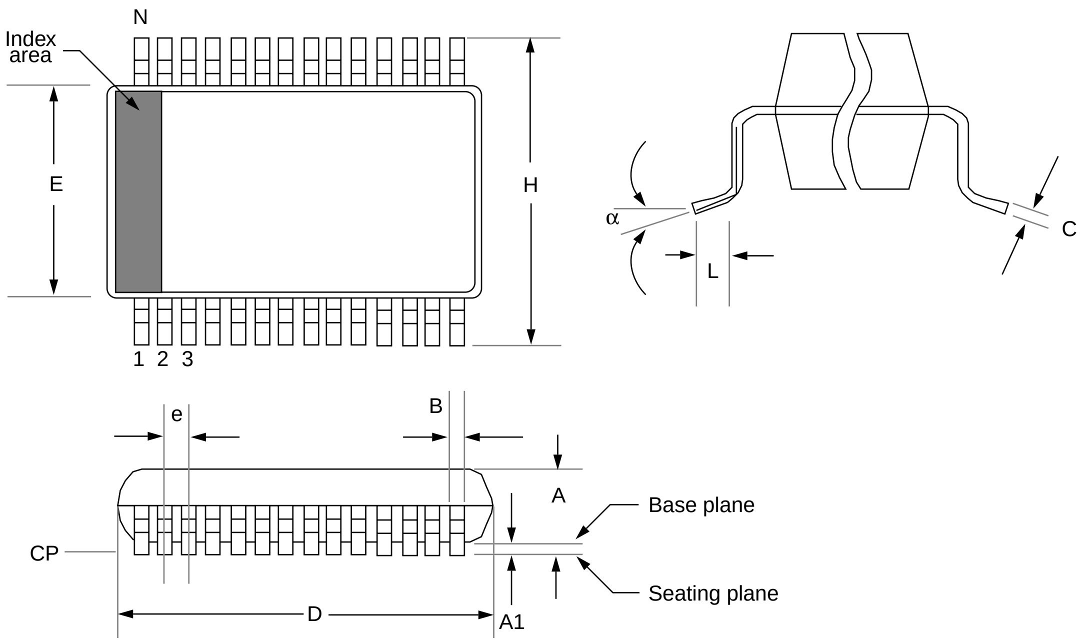


FIGURE 21-17: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



Data based on matrix samples. See first page of this section for details.

22.6 28-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)



Package Group: Plastic SSOP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	1.730	1.990		0.068	0.078	
A1	0.050	0.210		0.002	0.008	
B	0.250	0.380		0.010	0.015	
C	0.130	0.220		0.005	0.009	
D	10.070	10.330		0.396	0.407	
E	5.200	5.380		0.205	0.212	
e	0.650	0.650	**Reference**	0.026	0.026	**Reference**
H	7.650	7.900		0.301	0.311	
L	0.550	0.950		0.022	0.037	
N	28	28		28	28	
CP	-	0.102		-	0.004	

APPENDIX C: WHAT'S NEW

Added the following devices:

- PIC16C76
- PIC16C77

Removed the PIC16C710, PIC16C71, PIC16C711 from this datasheet.

Added PIC16C76 and PIC16C77 devices. The PIC16C76/77 devices have 368 bytes of data memory distributed in 4 banks and 8K of program memory in 4 pages. These two devices have an enhanced SPI that supports both clock phase and polarity. The USART has been enhanced.

When upgrading to the PIC16C76/77 please note that the upper 16 bytes of data memory in banks 1,2, and 3 are mapped into bank 0. This may require relocation of data memory usage in the user application code.

Added Q-cycle definitions to the Instruction Set Summary section.

APPENDIX D: WHAT'S CHANGED

Minor changes, spelling and grammatical changes.

Added the following note to the USART section. This note applies to all devices except the PIC16C76 and PIC16C77.

For the PIC16C73/73A/74/74A the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information or use the PIC16C76/77.

Divided SPI section into SPI for the PIC16C76/77 and SPI for all other devices.

LIST OF TABLES